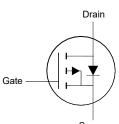
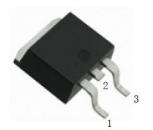
P-Channel Enhancement Mode MOSFET

Features

- Surface-mounted package
- Low Gate-Source Threshold Voltage
- Halogen and Antimony Free(HAF), **RoHS** compliant





Source

1.Gate 2.Drain 3.Source TO-252 Plastic Package

Key Parameters							
Parameter	Value	Unit					
-BV _{DSS}	100	V					
R _{DS(ON)} Max	700 @ -V _{GS} = 10 V	mΩ					
	720 @ -V _{GS} = 4.5 V	11122					
-V _{GS(th)} typ	1.8	V					
Q _g typ	6.8 @ -V _{GS} = 10 V	nC					

Absolute Maximum Ratings (at T_a = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	-V _{DS}	100	V	
Gate-Source Voltage	V _{GS}	± 20	V	
	T _c = 25°C T _c = 100°C	-I _D	3.2 2	А
Peak Drain Current, Pulsed 1)	-I _{DM}	9	А	
Single-Pulse Avalanche Current	-las	2.1	А	
Single-Pulse Avalanche Energy 2)	E _{AS}	1.1	mJ	
Power Dissipation	PD	16.2	W	
Operating Junction and Storage Temperature	TJ, Tstg	- 55 to + 150	C°	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	R _{eJC}	7.7	°C/W
Thermal Resistance from Junction to Ambient ³⁾	R _{0JA}	42	°C/W

¹⁾ Pulse Test: Pulse Width \leq 100 µs, Duty Cycle \leq 2%, Repetitive rating, pulse width limited by junction temperature T_{J(MAX)} = 150°C.

 $^{2)}$ Limited by T_{J(MAX)}, starting T_J = 25°C, L = 0.5 mH, R_g = 25 Ω , -I_D = 2.1 A, -V_{GS} = 10 V.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



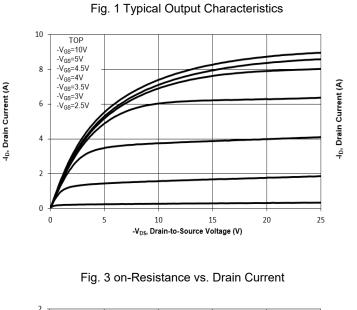
WTR10P6K2LS-HAF

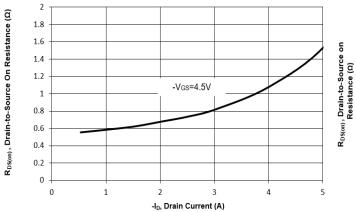
Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $-I_D = 250 \ \mu A$	-BV _{DSS}	100	-	-	V
Drain-Source Leakage Current at -V _{DS} = 100 V	-I _{DSS}	-	-	1	μA
Gate Leakage Current at V _{GS} = ± 20 V	lgss	-	-	± 100	nA
Gate-Source Threshold Voltage at V_{DS} = V_{GS} , -I _D = 250 µA	$-V_{GS(th)}$	1.2	-	2.5	V
Drain-Source On-State Resistance at $-V_{GS} = 10 \text{ V}, -I_D = 3 \text{ A}$ at $-V_{GS} = 4.5 \text{ V}, -I_D = 2 \text{ A}$	R _{DS(on)}	-	640 -	700 720	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at $-V_{DS} = 5 V$, $-I_D = 2 A$	g fs	-	4	-	S
Gate Resistance at V _{GS} = 0 V, V _{DS} = 0 V, f = 1 MHz	Rg	-	9	-	Ω
Input Capacitance at -V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	Ciss	-	388	-	pF
Output Capacitance at $-V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	Coss	-	18	-	pF
Reverse Transfer Capacitance at $-V_{DS} = 50 V$, $V_{GS} = 0 V$, f = 1 MHz	Crss	-	13	-	pF
Total Gate Charge at -V _{GS} = 10 V, -V _{DS} = 50 V, -I _D = 3 A at -V _{GS} = 4.5 V, -V _{DS} = 50 V, -I _D = 3 A	Qg	-	6.8 3	-	nC
Gate-Source Charge at $-V_{GS} = 10 \text{ V}, -V_{DS} = 50 \text{ V}, -I_D = 3 \text{ A}$	Q _{gs}	-	1.7	-	nC
Gate-Drain Charge at $-V_{GS}$ = 10 V, $-V_{DS}$ = 50 V, $-I_D$ = 3 A	Q _{gd}	-	0.9	-	nC
Turn-On Delay Time at -V _{GS} = 10 V, -V _{DS} = 50 V, -I _D = 3 A, R _G = 3.3 Ω	t _{d(on)}	-	6	-	ns
Turn-On Rise Time at -V _{GS} = 10 V, -V _{DS} = 50 V, -I _D = 3 A, R _G = 3.3 Ω	tr	-	2.8	-	ns
Turn-Off Delay Time at -V _{GS} = 10 V, -V _{DS} = 50 V, -I _D = 3 A, R _G = 3.3 Ω	$t_{d(\text{off})}$	-	7.5	-	ns
Turn-Off Fall Time at -V _{GS} = 10 V, -V _{DS} = 50 V, -I _D = 3 A, R _G = 3.3 Ω	t _f	-	7	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $-I_S = 1 A$, $V_{GS} = 0 V$	-V _{SD}	-	-	1.2	V
Body-Diode Continuous Current	-ls	-	-	3.2	А
Body-Diode Continuous Current, Pulsed	-Ism	-	-	9	А
Body Diode Reverse Recovery Time at -Is = 3 A, di/dt = 100 A / μs	trr	-	19.7	-	ns
Body Diode Reverse Recovery Charge at -Is = 3 A, di/dt = 100 A / µs	Qrr	-	18.2	-	nC



Electrical Characteristics Curves







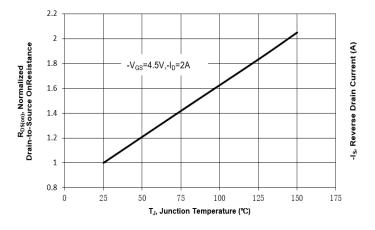
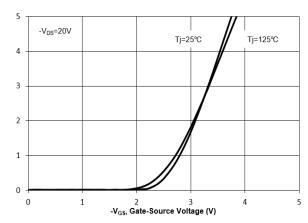
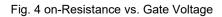


Fig. 2 Typical Transfer Characteristics





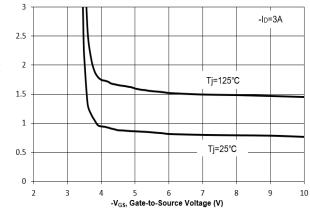
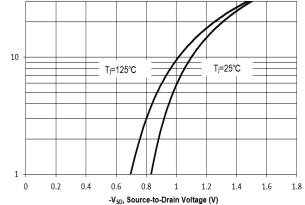
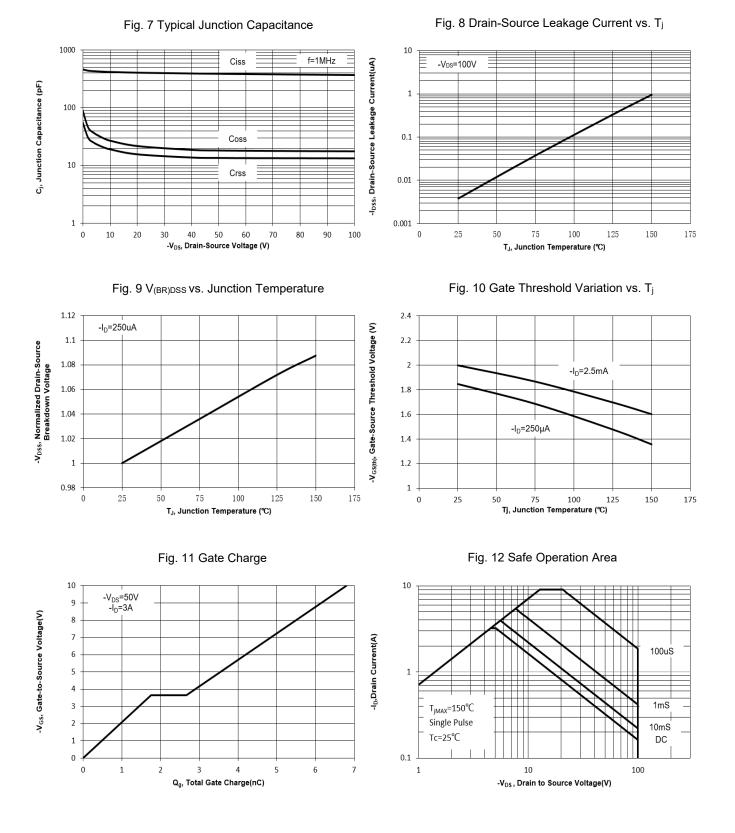


Fig. 6 Typical Body-Diode Forward Characteristics





Electrical Characteristics Curves





Electrical Characteristics Curves

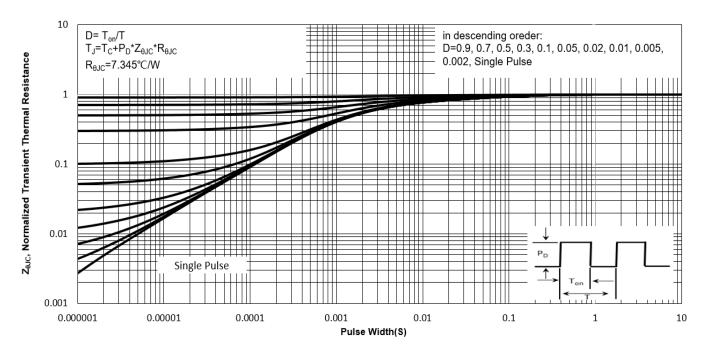
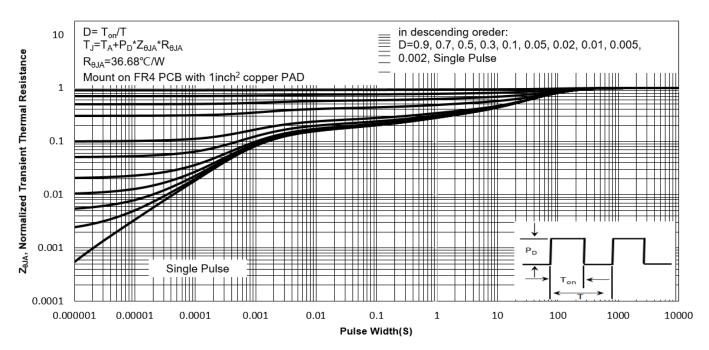




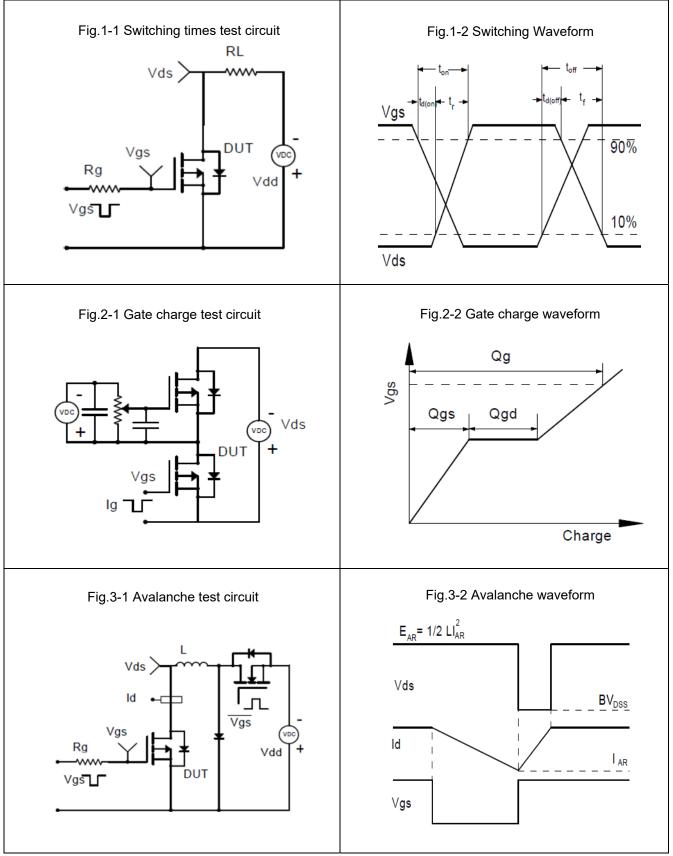
Fig. 14 Normalized Maximum Transient Thermal Impedance(z_{BJA})





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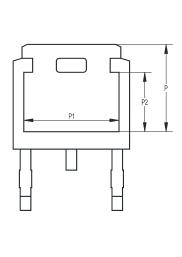
Test Circuits

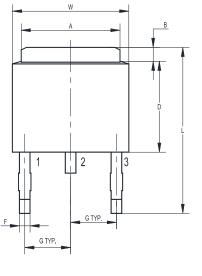


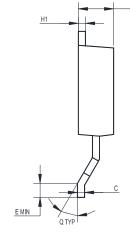


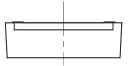
Package Outline (Dimensions in mm)

Н



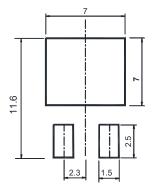






UNIT	Α	В	С	D	Е	F	G	W	Н	H1	Q	L	Р	P1	P2
	5.5	1.20	0.65	6.2	0.8	1.0	2.3	6.7	2.5	0.65	60°	10.7	5.4	5.0	3.4
mm	4.9	0.85	0.4	5.6	MIN	0.5	TYP	6.1	2.1	0.4	TYP	9	5.0	4.6	2.9

Recommended Soldering Footprint



Packing information

Tape Width		Pit	tch	Reel	Size	Per Reel Packing Quantity	
Package	(mm)	mm	inch	mm	inch		
TO-252	12	8 ± 0.1	0.315 ± 0.004	330	13	2,500	

Marking information

" TR10P6K2LS " = Part No.

" ****** " = Date Code Marking Font type: Arial





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